



**SIDDHARTH INSTITUTE OF ENGINEERING & TECHNOLOGY::
PUTTUR**

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QUESTION BANK (DESCRIPTIVE)

Subject with Code: VLSITechnology(20EC4201)

Year & Sem: I-M.Tech& I-Sem

Course & Branch: M.Tech-VLSI

Regulation: R20

UNIT-I

REVIEW OF MICROELECTRONICS AND INTRODUCTION TO MOS TECHNOLOGIES

1.	a)	Explain different steps involved in preparation CMOS using twin tub process.	[L2][CO1]	[8M]
	b)	Define Figure of merit and gds.	[L1][CO1]	[4M]
2.		Derive the relation between drain to source current I_{ds} VS drain to source voltage V_{ds} in non saturated and saturated.	[L4][CO1]	[12M]
3.	a)	Compare CMOS and Bi-CMOS.	[L2][CO1]	[7M]
	b)	Write short notes on latch-up in CMOS circuits.	[L2][CO1]	[5M]
4.		Determine the Pull-up and Pull-down ratio for NMOS inverter through one (or) more pass transistors.	[L5][CO1]	[12M]
5.	a)	What is meant by body effect?	[L2][CO1]	[6M]
	b)	Explain a Bi-CMOS inverter with a neat sketch.	[L2][CO1]	[6M]
6.	a)	Illustrate the main steps in a typical N-WELL process.	[L2][CO1]	[6M]
	b)	Briefly discuss about the pass transistor.	[L2][CO1]	[6M]
7.	a)	Compare NMOS and CMOS technology.	[L2][CO1]	[6M]
	b)	Derive the expression for ZPU/ZPD.	[L4][CO1]	[6M]
8.	a)	Define the term Threshold voltage of MOSFET and explain its significance	[L1][CO1]	[6M]
	b).	Explain the NMOS depletion mode transistor.	[L2][CO1]	[6M]
9	a)	Explain about the Structure of NMOS transistor	[L2][CO1]	[8M]
	b)	Explain the operation of CMOS inverter with a logic diagram.	[L2][CO1]	[4M]
10	a)	Explain about NMOS inverter with neat sketch	[L2][CO1]	[6M]
	b)	Define electrical properties of MOS circuits.	[L2][CO1]	[6M]

UNIT -II**LAYOUT DESIGN AND TOOLS\LOGIC GATES & LAYOUTS**

1.	a)	Explain how stick diagrams can be used for layout diagrams.	[L1][CO2]	[8M]
	b)	Discuss the wiring capacitance	[L6][CO2]	[4M]
2.	a)	Explain about static complementary gates.	[L2][CO2]	[6M]
	b)	What are the different strategies for building low power gates? Explain.	[L1][CO2]	[6M]
3.	a)	Differentiate switch logic and gate logic. .	[L4][CO2]	[6M]
	b)	List the salient features of sub system layout.	[L1][CO2]	[6M]
4.	a)	Explain clearly the Scalable design rules.	[L2][CO2]	[6M]
	b)	Explain clearly Wires and Vias in VLSI design	[L2][CO2]	[6M]
5.		Design the static complementary pull-up and pull-down networks for AOI expression	[L6][CO2]	[12M]
6.		Define the following terms .		
	a)	Speed power product.	[L1][CO2]	[5M]
	b)	Delay through RC transition time	[L1][CO2]	[7M]
7.	a)	Explain briefly about Resistive Inter-Connect delay and RC Trees delay	[L2][CO2]	[6M]
	b)	Explain about driving large loads with diagram	[L2][CO2]	[6M]
8.		What are layout design rules? Explain the layer representations and based design rules for CMOS process.	[L1][CO2]	[12M]
9.	a)	Implement NAND gate in NMOS technology and hence draw its stick diagram and design a layout for the stick diagram	[L3][CO2]	[6M]
	b)	Discuss about the effects of scaling down the dimensions of MOS circuits and Systems.	[L6][CO2]	[6M]
10.	a)	Explain switch Logic and Alternative Logic.	[L2][CO2]	[6M]
	b)	Briefly discuss about the combinational logic function.	[L2][CO2]	[6M]

UNIT –III**COMBINATIONAL LOGIC NETWORKS\SEQUENTIAL SYSTEMS**

1.	a)	Explain in detail about the requirements in designing logic networks using realistic interconnect models	[L2][CO3]	[6M]
	b)	Draw the single row layout design.	[L2][CO3]	[6M]
2.	a)	Explain briefly about power optimization.	[L2][CO3]	[6M]
	b)	Draw the switch implementation of a multiplexer	[L2][CO3]	[6M]
3.	a)	Briefly discuss about crosstalk minimization	[L2][CO3]	[6M]
	b)	Briefly discuss about Fanout with diagram.	[L2][CO3]	[6M]
4.	a)	Write short notes on power optimization of combinational logic networks.	[L1][CO3]	[6M]
	b)	Explain path delay with respect to combination networks delay.	[L2][CO3]	[6M]
5.	a)	Explain the clocking disciplines and power optimization in sequential systems.	[L2][CO3]	[6M]
	b)	What are the various simulators used for combinational logic?	[L1][CO3]	[6M]
6.	a)	Explain clearly about switch simulation.	[L2][CO3]	[6M]
	b)	Explain about the combinational network testing.	[L2][CO3]	[6M]
7.		Draw the layout diagram of three input NAND gate in CMOS.	[L2][CO3]	[12M]
8.		What is simulation? Explain about various types of simulation applied at different levels of fabrication.	[L1][CO3]	[12M]
9.	a)	With suitable examples explain about network delays combinational logic circuits.	[L2][CO3]	[6M]
	b)	Implement an 'n-bit' shift register and explain its operation over one clock cycle	[L3][CO3]	[6M]
10.	a)	Discuss briefly about standard cell layout design.	[L6][CO3]	[6M]
	b)	Briefly explain the block diagram of phase locked loop for clock generation	[L2][CO3]	[6M]

UNIT-IV**FLOORPLANNING AND ARCHITECTURE DESIGN**

1.	a)	Briefly discuss about floor planning methods.	[L2][CO4]	[6M]
	b)	Draw and explain the block placement and channel definition	[L2][CO4]	[6M]
2.	a)	Write a short notes on global routing.	[L1][CO4]	[6M]
	b)	Explain the concept of switch box routing	[L2][CO4]	[6M]
3.	a)	Discuss about different floor planning tips.	[L6][CO4]	[6M]
	b)	Write a short notes on design validation.	[L1][CO4]	[6M]
4.	a)	Explain about placement and routing at chip level design	[L2][CO4]	[6M]
	b)	Explain about architecture testing	[L2][CO4]	[6M]
5.	a)	Discuss about off-chip connections and packages.	[L6][CO4]	[8M]
	b)	Draw and explain the power line inductance	[L2][CO4]	[6M]
6.	a)	Draw and explain the I/O architecture with a neat sketch	[L2][CO4]	[6M]
	b)	Explain the concept of pad design with a diagram.	[L2][CO4]	[6M]
7.		Explain the concept of register transfer design with data path control architecture	[L2][CO4]	[12M]
8.		With a flowchart explain the concept of ASM chart design.	[L2][CO4]	[12M]
9.	a)	Discuss high level synthesis.	[L6][CO4]	[6M]
	b)	Write a short notes on power down modes.	[L1][CO4]	[6M]
10.	a)	Explain the architecture for low power with a diagram.	[L2][CO4]	[6M]
	b)	Write a notes on linear feedback shift register.	[L2][CO4]	[6M]

UNIT-V**INTRODUCTION TO CADSYSTEM AND CHIPDESIGN****Prepared By:**

1.		Write about the following.		
	a)	Hardware-software co-design.	[L2][CO5]	[6M]
	b)	Floor planning methods	[L2][CO5]	[6M]
2.	a)	Write a short notes on layout synthesis.	[L2][CO5]	[6M]
	b)	Discuss about global routing.	[L6][CO5]	[6M]
3.	a)	With an example give the method involved in the chip design	[L2][CO5]	[8M]
	b)	Briefly discuss about CAD system	[L2][CO5]	[4M]
4.	a)	Explain about system on chips and embedded CPUs.	[L2][CO5]	[6M]
	b)	Write a notes on logic synthesis.	[L2][CO5]	[6M]
5.		With a diagram explain about detailed routing method.	[L2][CO5]	[12M]
6.	a)	Explain the timing analysis and optimization process.	[L2][CO5]	[6M]
	b)	Write about test generation pattern.	[L2][CO5]	[6M]
7.	a)	Explain the technology independent logic optimization.	[L2][CO5]	[8M]
	b)	Draw the diagram of irredundant-reduced cycle.	[L2][CO5]	[4M]
8.	a)	Write a short notes on sequential machine optimizations.	[L1][CO5]	[6M]
	b)	Explain about scheduling ad binding.	[L1][CO5]	[6M]
9	a)	Write about switch level simulation.	[L1][CO5]	[4M]
	b)	Write a short notes on chip level placement.	[L1][CO5]	[8M]
10.		Explain about technology dependent logic optimization.	[L2][CO5]	[12M]

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